Financial Results Briefing for FYE 12/2025

February 13, 2026

MEC COMPANY LTD.

Securities code: 4971

https://www.mec-co.com/en/

Note : This document has been translated from the Japanese original for reference purposes only. In the event of any discrepancy between this translated document and the Japanese original, the original shall prevail.

FYE12/2025 Key Factors

1. Sales: 20,947 million yen (YOY change: Up 14.9%)
   Operating income: 5,748 million yen (YOY change: Up 26.0%)

2. Exchange rate impact (YOY change)
   Sales: Up 134 million yen,
   Operating income: Up 67 million yen.

3. Chemicals
   Sales: 20,211 million yen (YOY change: Up 15.6%)
   Shipments: 47,717 ton (YOY change: Up 13.4%)

4. Major products sales (YOY change)
   CZ: Up 19.8% EXE: Up 4.9% V-Bond: Up 1.1% SF: Down 30.5%

Exchange Rates

Unit : yen

	Initial forecast	Q4 FYE12/2025	Q4 FYE12/2024	Q3 FYE12/2025
N T D	4.76	4.81	4.72	4.75
R M B	21.08	20.94	21.04	20.60
H K D	19.48	19.30	19.41	19.08
T H B	4.22	4.57	4.31	4.48
E U R	164.84	169.14	163.79	165.47
U S D	152.33	150.40	151.44	148.79

- Overseas subsidiaries are basically transactions denominated in local currency, and are affected by the yen / local currency rate when converting to yen in consolidated accounting.
- Our major foreign currencies are the Taiwan dollar (NTD) and the Chinese yuan (RMB). Both use the average rate during the period.

Exchange sensitivity (FY2025)

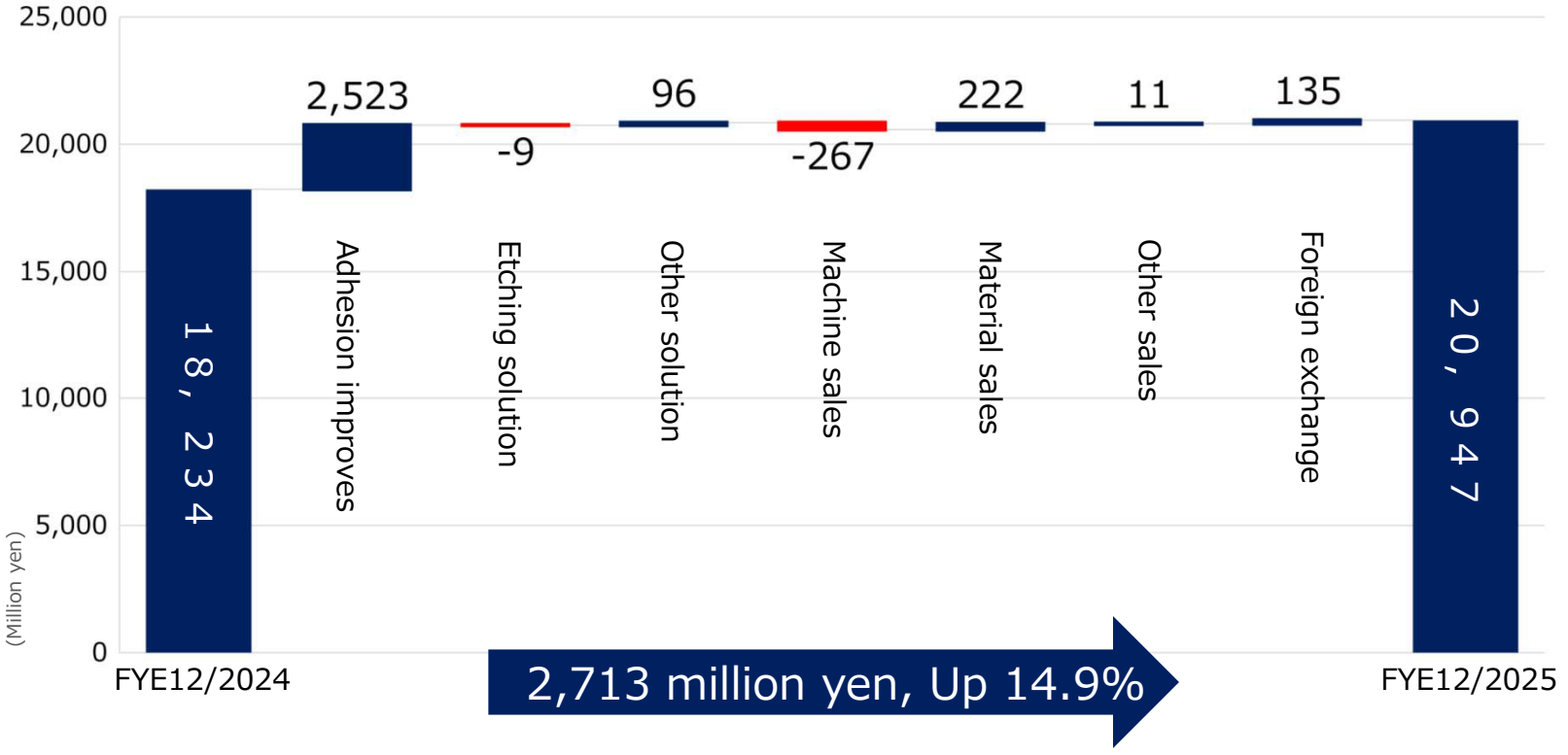
NTD:	(Sale)	80 million yen
	(Operating income)	59 million yen
RMB:	(Sale)	32 million yen
	(Operating income)	17 million yen

FYE12/2025 Results

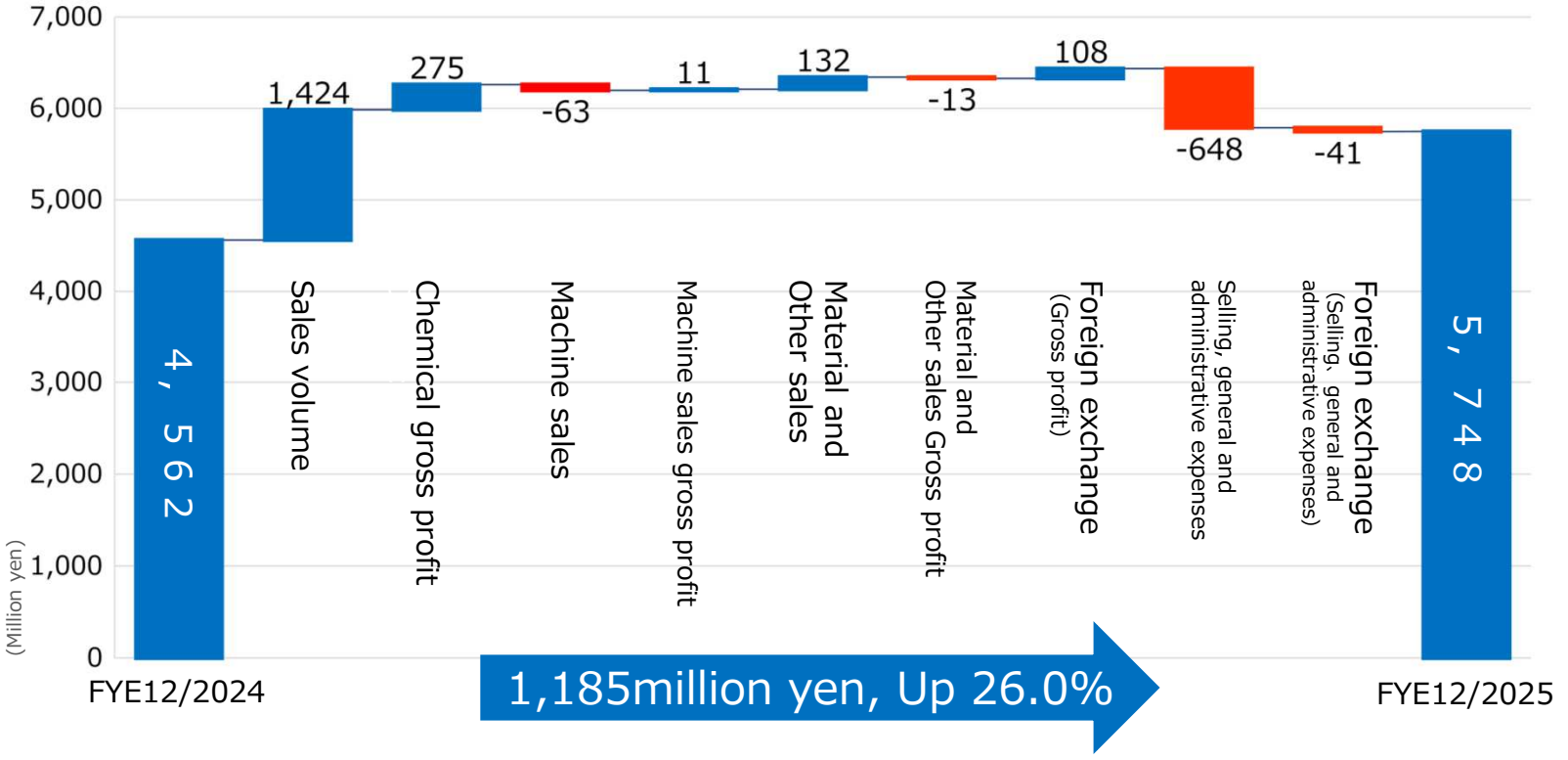
Unit : million yen

	FYE12.2024 Results	FYE12.2025 Results	FYE12.2025 YOY	FYE12.2025 YOY (%)
Net sales	18,234	20,947	2,713	14.9%
Chemical sales	17,478	20,211	2,733	15.6%
Gross profit	11,101	12,977	1,875	16.9%
Gross profit margin	60.9%	62.0%	1.1ppt	-
SGA	6,539	7,229	689	10.6%
Sales ratio	35.9%	34.5%	-1.4ppt	-
Operating income	4,562	5,748	1,185	26.0%
Operating profit margin	25.0%	27.4%	2.4ppt	-
Ordinary income	4,682	6,051	1,368	29.2%
Ordinary profit margin	25.7%	28.9%	3.2ppt	-
Profit before tax	4,669	6,473	1,803	-
Net income	2,291	5,028	2,736	119.4%
EBITDA	5,487	7,302	1,815	36.1%
Net income per share	122.38	272.14	-	-
ROE	8.9%	17.5%	8.6ppt	-

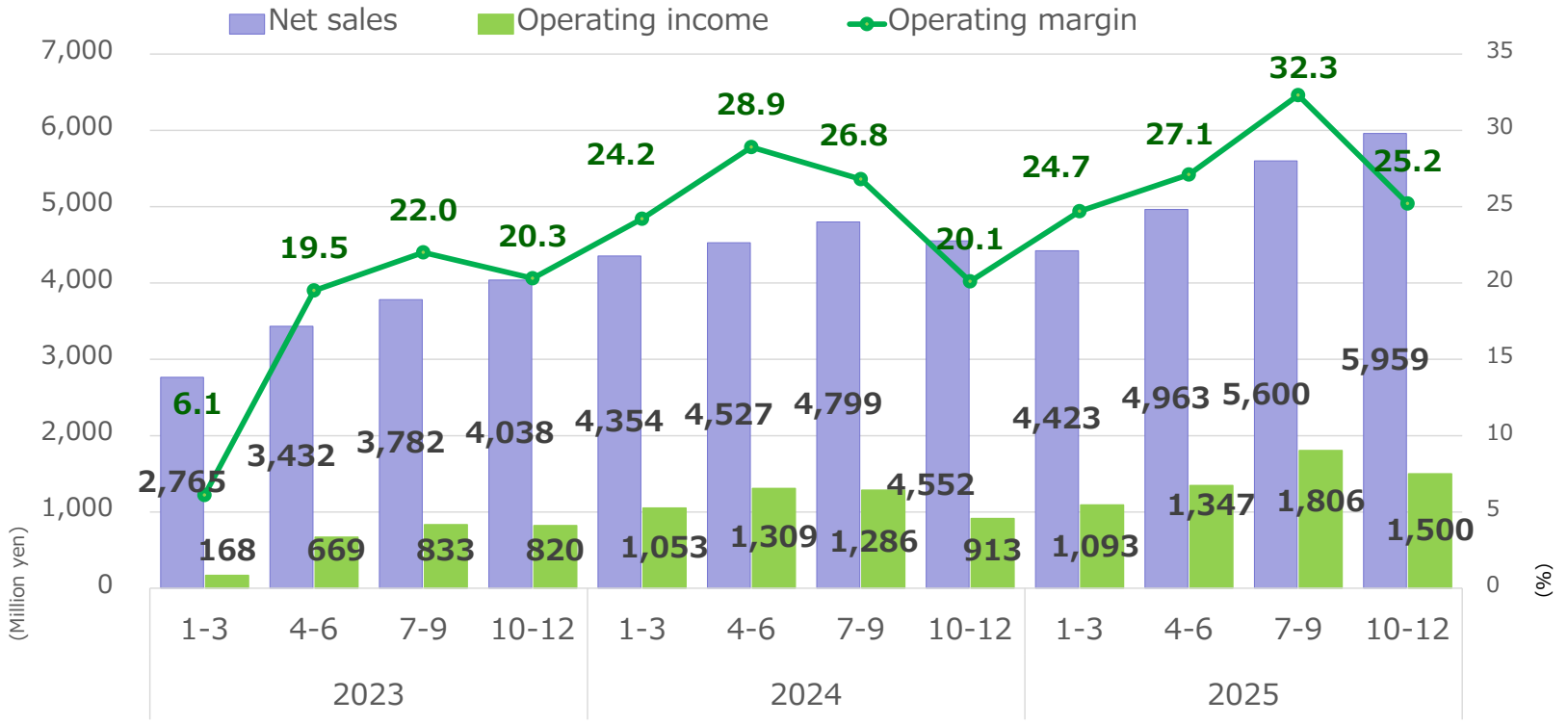
Net Sales YOY



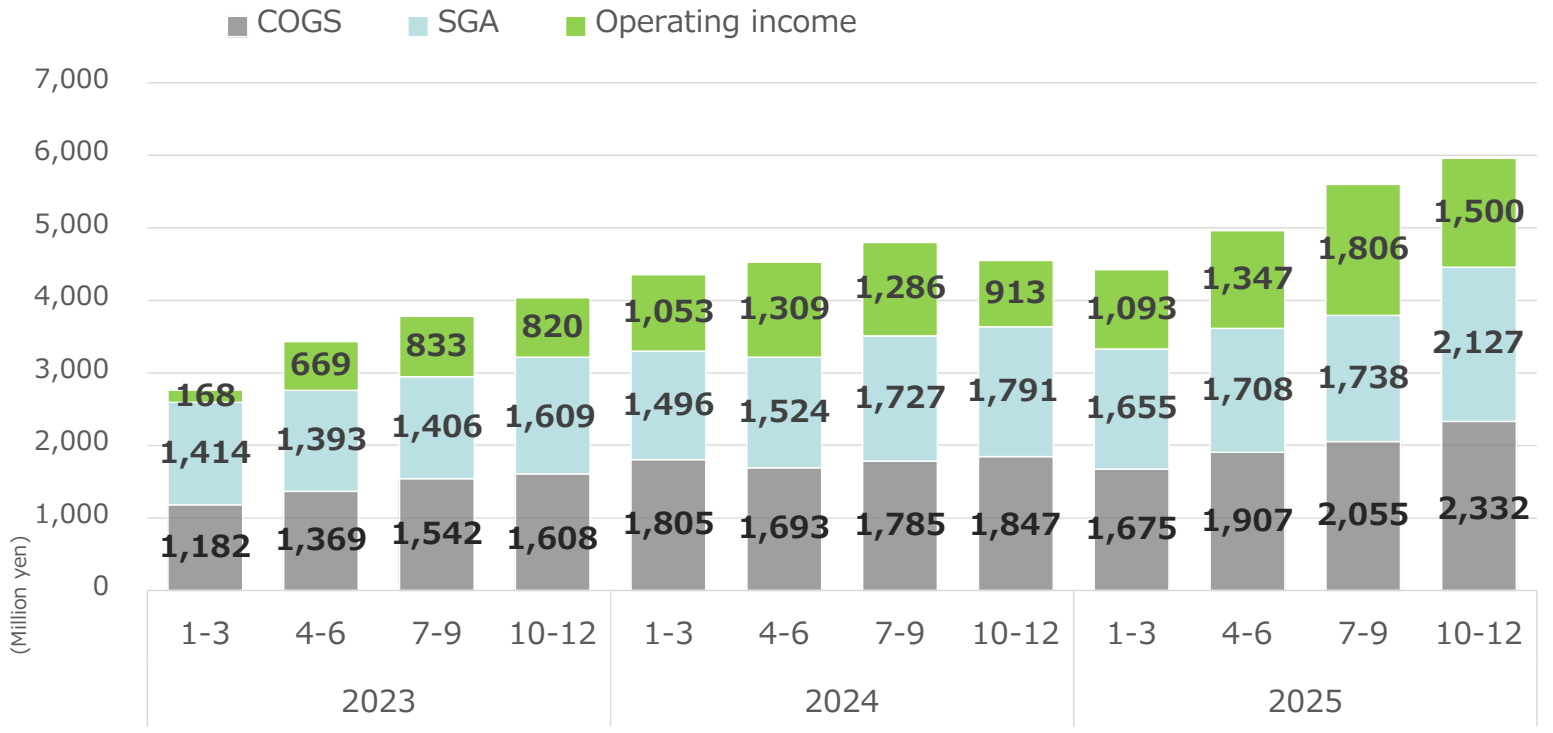
Operating Income YOY



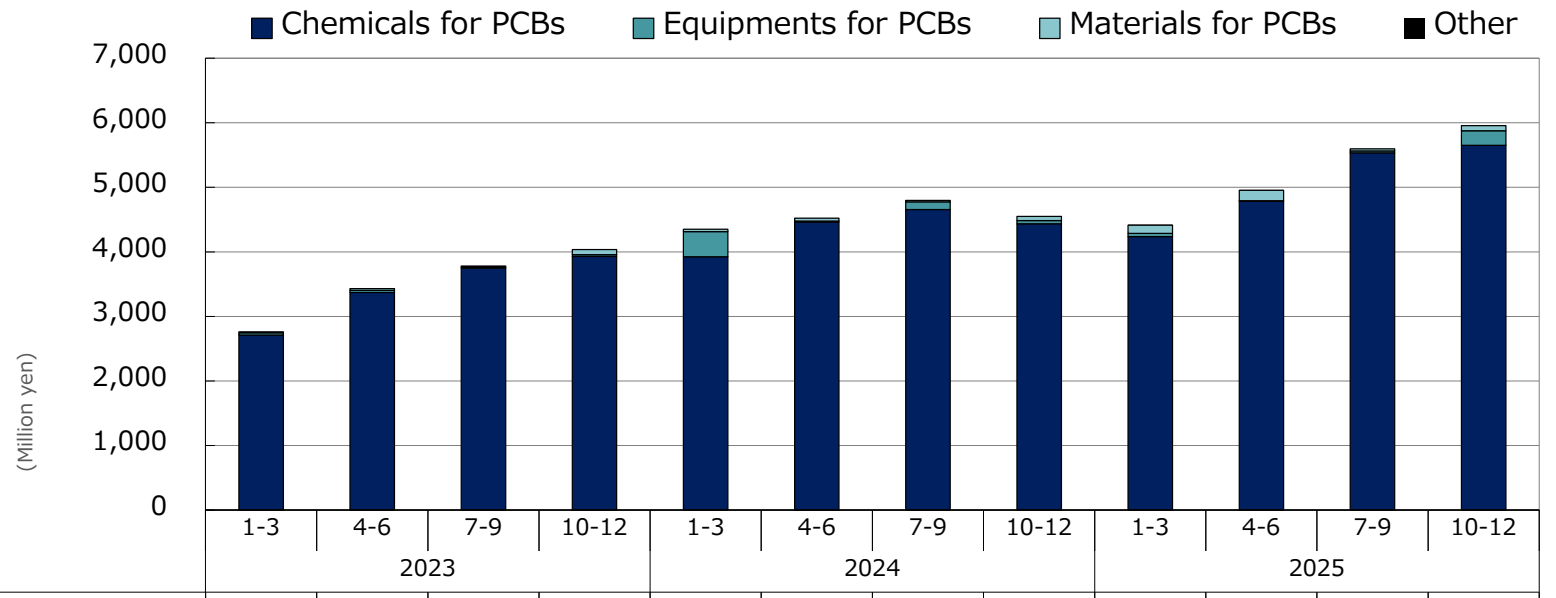
Quarterly Performance:
Sales, Operating Income, Operating Margin (Consolidated)



Quarterly Composition: Operating Income, SG&A, CODS (Consolidated)

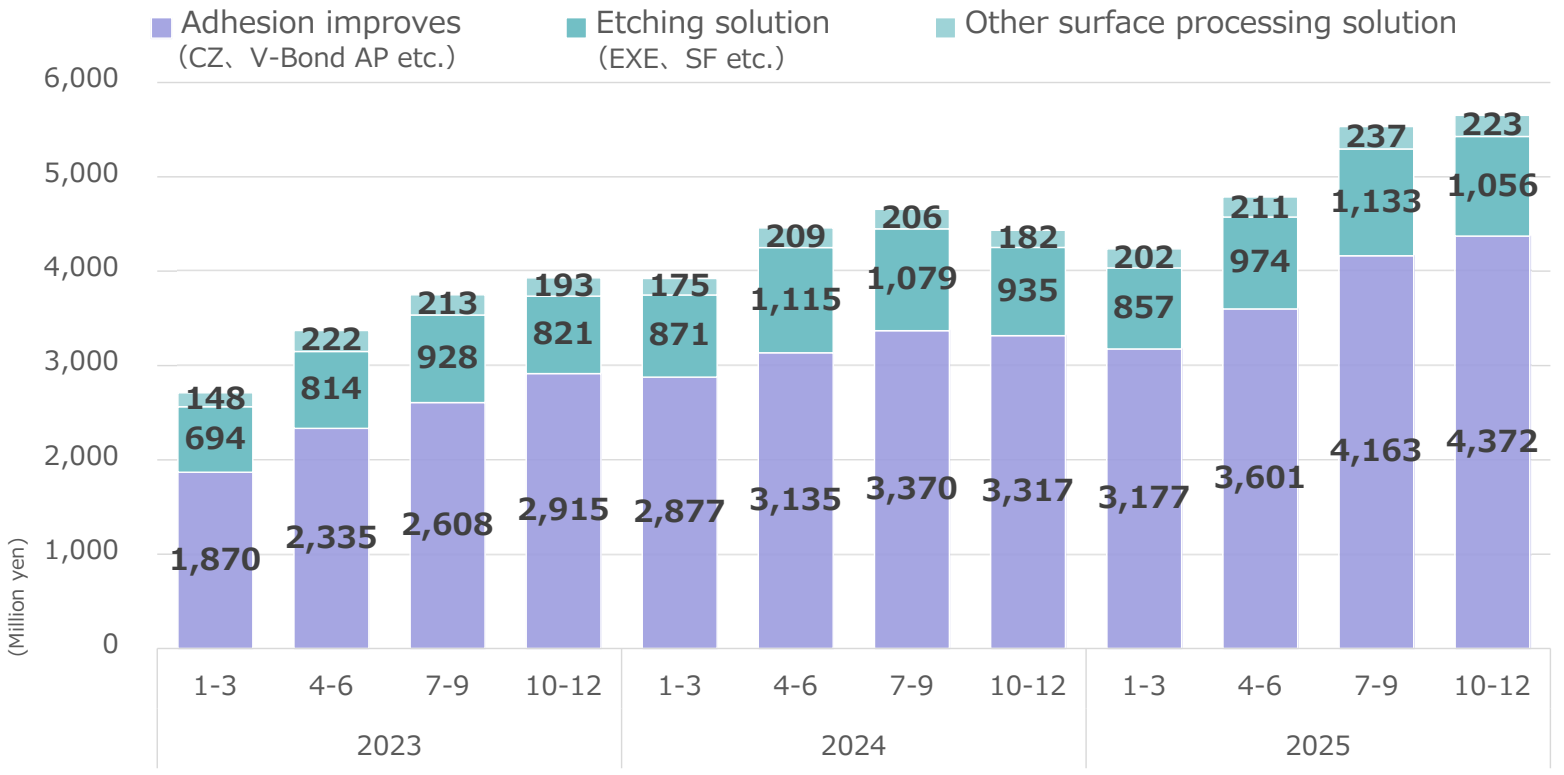


Quarterly Performance : Product-Specific Sales (Consolidated)

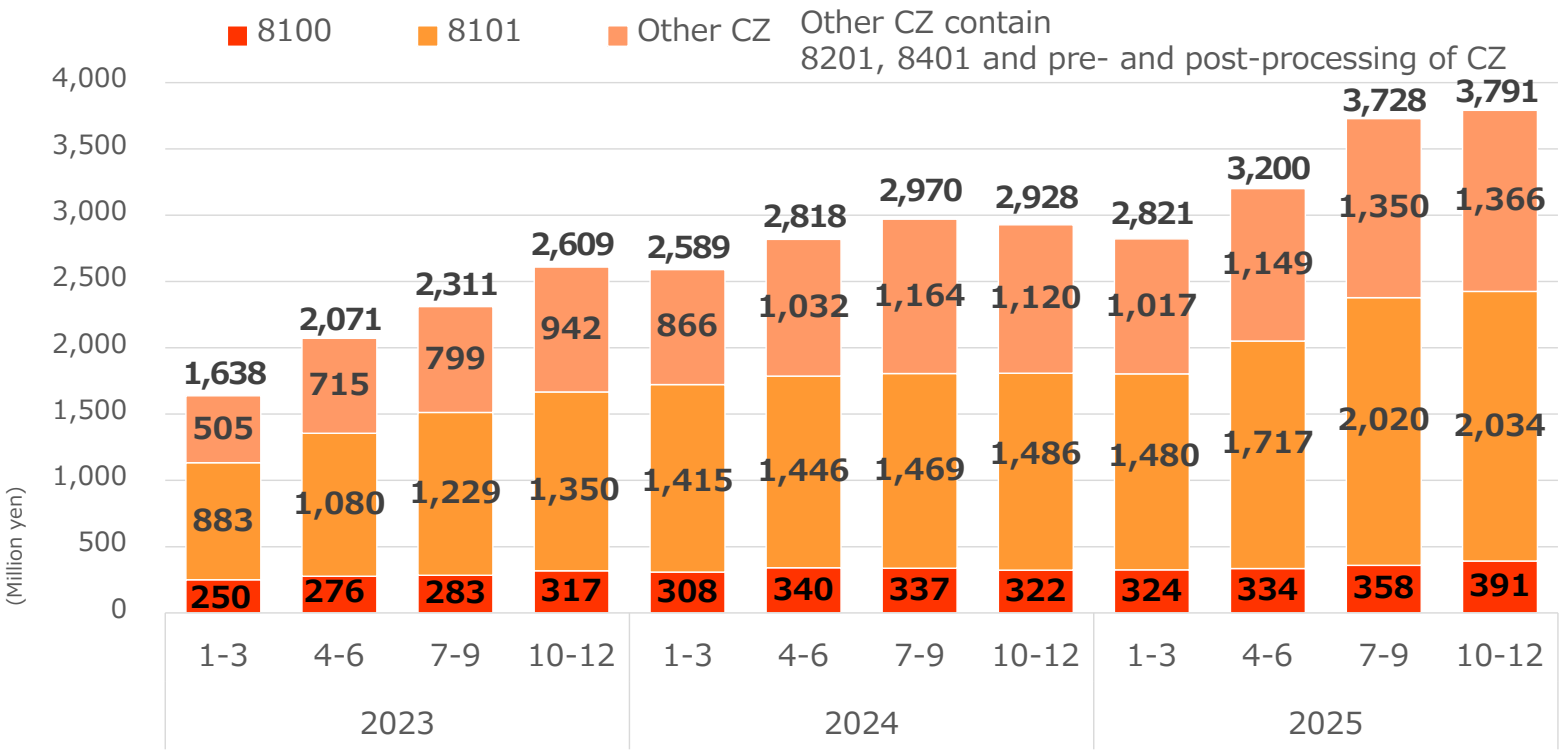


	2023				2024				2025			
	1-3	4-6	7-9	10-12	1-3	4-6	7-9	10-12	1-3	4-6	7-9	10-12
Other	1	1	0	0	1	3	1	1	8	7	2	1
Materials for PCBs	16	27	15	80	37	44	22	64	128	160	33	80
Equipments for PCBs	34	31	17	28	391	19	118	49	49	7	30	225
Chemicals for PCBs	2,712	3,372	3,749	3,929	3,924	4,460	4,657	4,436	4,237	4,787	5,534	5,652

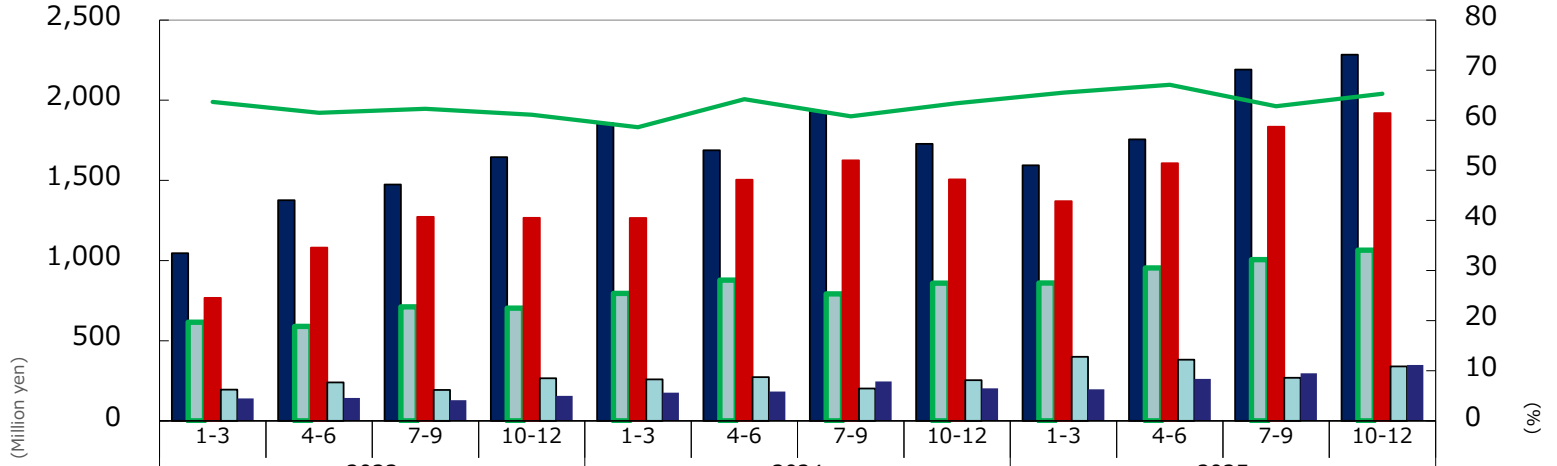
Quarterly Performance : Chemical Sales (Consolidated)



Quarterly Performance : CZ Series Sales



Quarterly Performance : Region-Specific Sales and Overseas Sales Ratio



	2023 1-3	2023 4-6	2023 7-9	2023 10-12	2024 1-3	2024 4-6	2024 7-9	2024 10-12	2025 1-3	2025 4-6	2025 7-9	2025 10-12
Japan	1,046	1,376	1,474	1,645	1,857	1,688	1,931	1,728	1,594	1,756	2,191	2,284
Taiwan	615	589	711	703	795	878	792	859	860	954	1,006	1,065
China	767	1,081	1,272	1,266	1,265	1,504	1,625	1,506	1,370	1,607	1,835	1,919
Europe	195	240	193	266	259	273	202	254	400	382	269	340
Thailand	140	143	129	156	176	183	246	203	197	262	297	349
Foregin sales ratio	63.7	61.5	62.3	61.1	58.6	64.2	60.8	63.4	65.5	67.1	62.8	65.3

Overseas sales ratio is 79.3%(same period of the previous year: 78.5%)
including sales to overseas customers through agents in Japan.

Our Future Plans

Our Future Plans

Business environment

- In the medium to long term, technological innovation is expected to advance against the backdrop of the ongoing digital revolution and the spread of technologies such as IoT, AI, 5G, electrification of vehicles, and the promotion of DX and GX, and markets related to our company are expected continue expanding.
- Demand for the related CZ series and chemical adhesion promoter is expected to increase, driven by ultra-high density, ultra-high frequency, and higher performance, as well as the rise in PKG substrates resulting from growing semiconductor demand.

Major chemical

CZ : In the short term, demand will be affected by trends in the semiconductor market. In the medium to long term, demand is expected to expand due to an increase in PKG substrates and advances in larger and more multilayered designs.

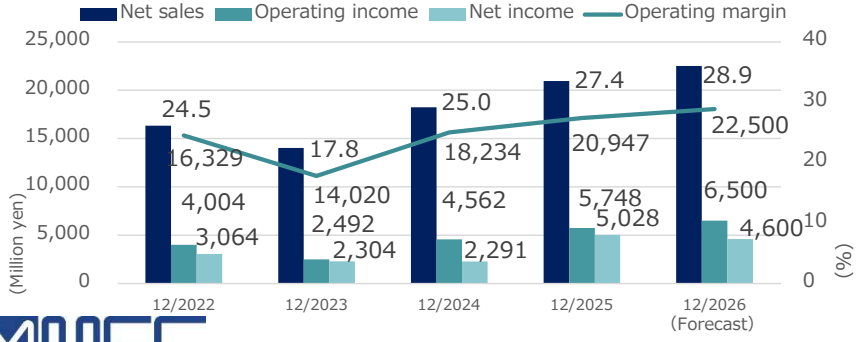
V-Bond : In the short term, recovery is expected in the automobile and smartphone markets. Demand for satellite communication boards is on an upward trend.

EXE : Demand will be affected by trends in the display market.

SF : Demand will be affected by trends in the tablet PC market.

FYE12/2026 Full-year Forecast

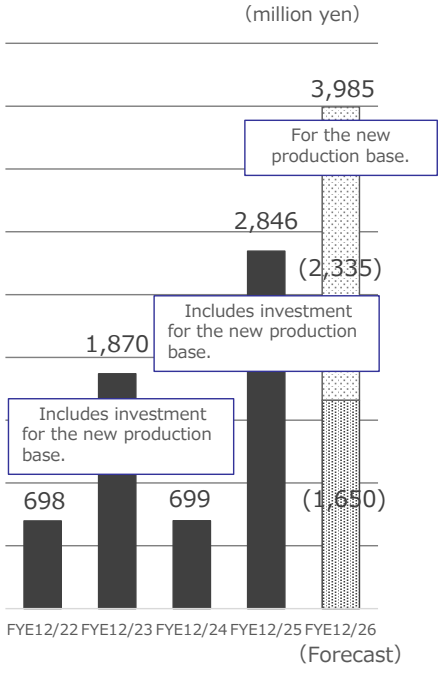
	FYE12/2025		FYE12/2026					
	Full-year		1H			Full-year		
	Amount (million yen)	Profit ratio (%)	Amount (million yen)	Profit ratio (%)	YOY change (%)	Amount (million yen)	Profit ratio (%)	YOY change (%)
Net sales	20,947	-	10,800	-	15.1	22,500	-	7.4
Operating income	5,748	27.4	3,000	27.8	22.9	6,500	28.9	13.1
Ordinary income	6,051	28.9	3,025	28.0	21.3	6,550	29.1	8.2
Net income	5,028	24.0	2,000	18.5	5.6	4,600	20.4	-8.5
Net income per share(yen)	272.14	-	109.53	-	-	251.91	-	-



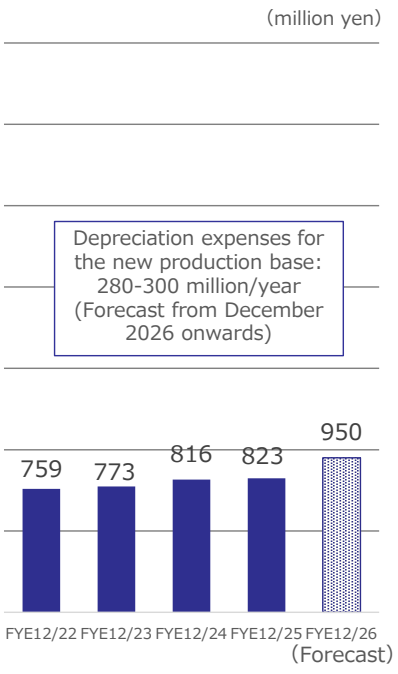
Exchange rates	FYE12/2025 Actual	FYE12/2026 Assumed
NTD	4.81	4.95
RMB	20.94	21.24
HKD	19.30	19.36
THB	4.57	4.67
EUR	169.14	175.76
USD	150.40	151.02

Capital Investment, Depreciation Expenses and R&D Expenses

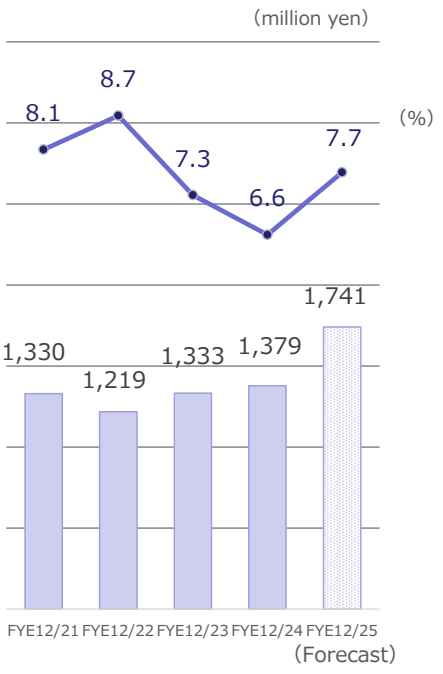
Capital investment



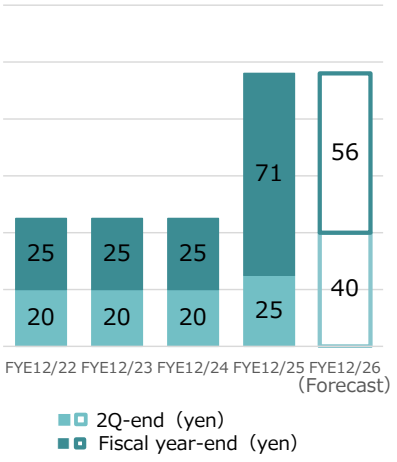
Depreciation expenses

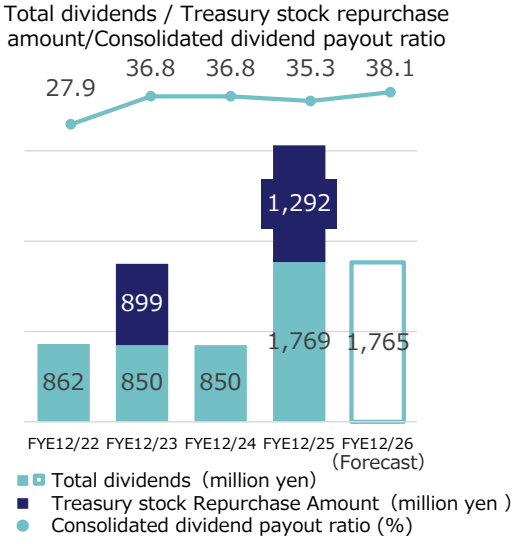


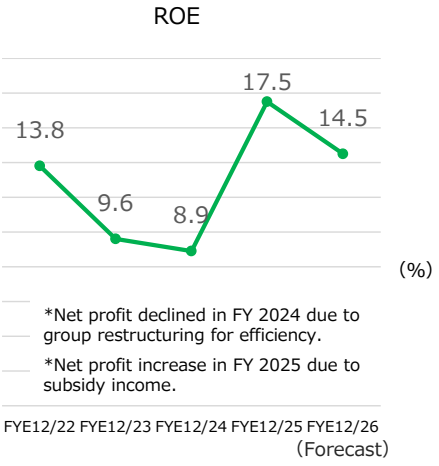
R&D expenses and Ratio of consolidated sales



Trends in Total Dividends, Consolidated Dividend Payout Ratio, and ROE







Shareholder Return Policy

- Consolidated dividend payout ratio:35% or higher, and
- DOE (Dividend on Equity): 4.0% or higher
- Share repurchases to be conducted flexibly depending on circumstances

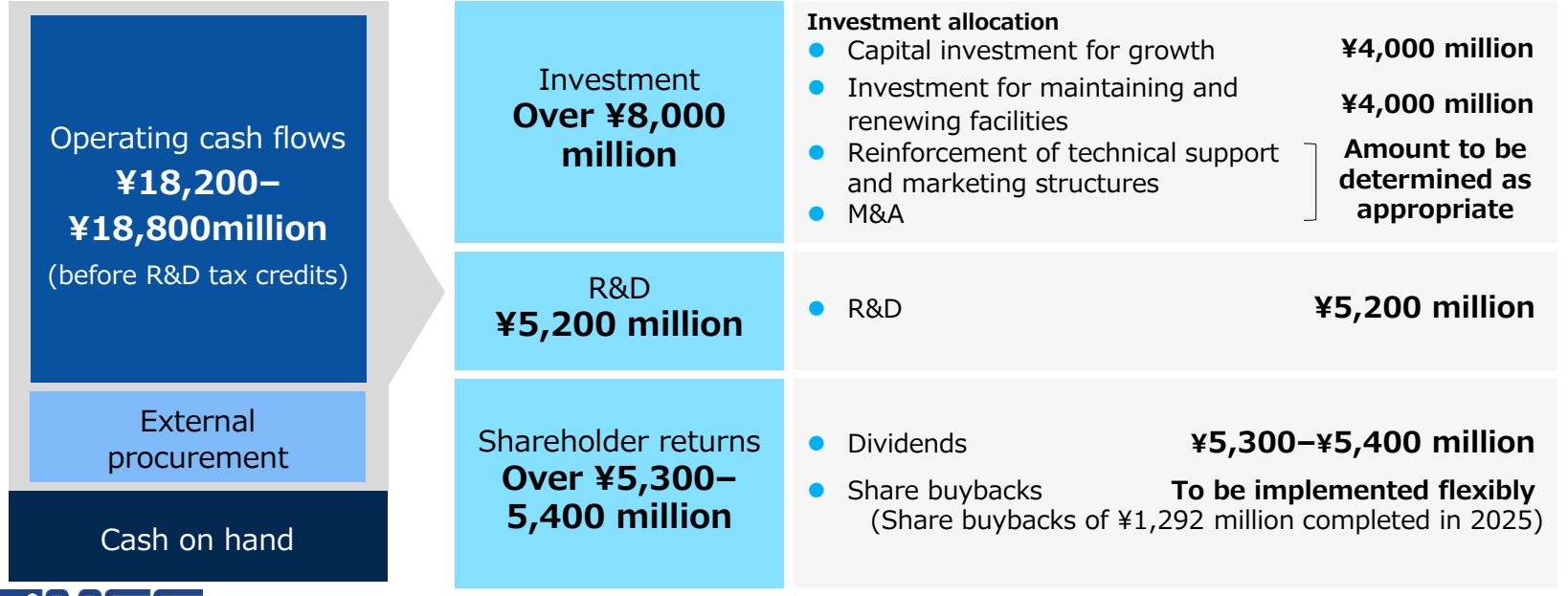
ROE

- 13% ～ 16%

Basic Policy on Cash Allocation

The basic policy on cash allocation for 2030 Vision: Phase 2 (cumulative for 2025–2027) is as follows.

*The size of each item is not an indicator of the amount.



ESG Effort

Environment

- Development of products that reduce environmental impact.
- Appropriate chemical substance management.
- Promotion of resource recycling.
- Measures to address climate change.

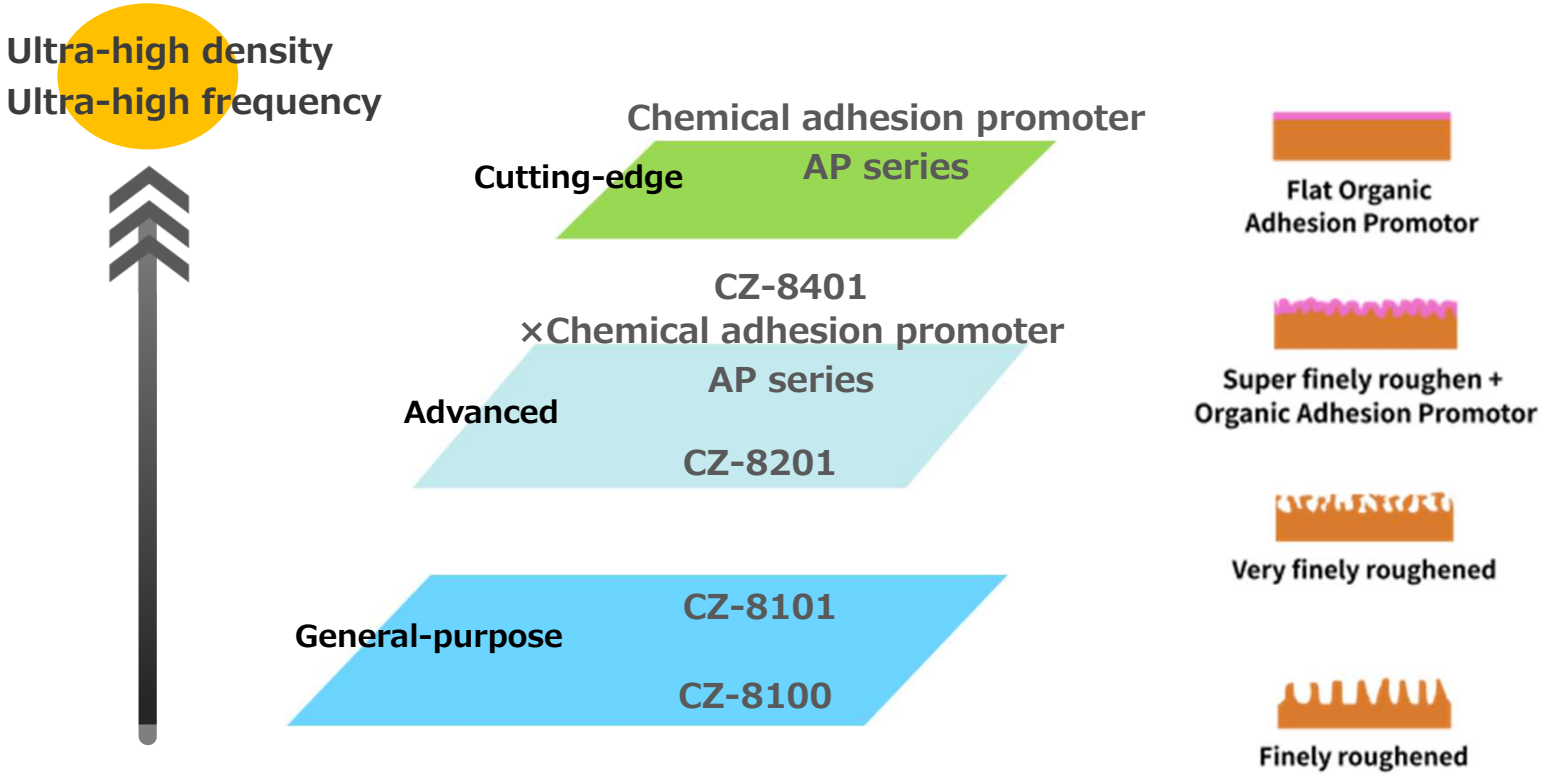
Social

- Human capital strategy.
- Utilization of diverse human resources (empowerment of women, WLB, promotion of men taking childcare leave, etc.).
- Contribution to social development (5G, autonomous driving).

Governance

- Reinforcement of management foundations (CG system, various committees, risk management, etc.).

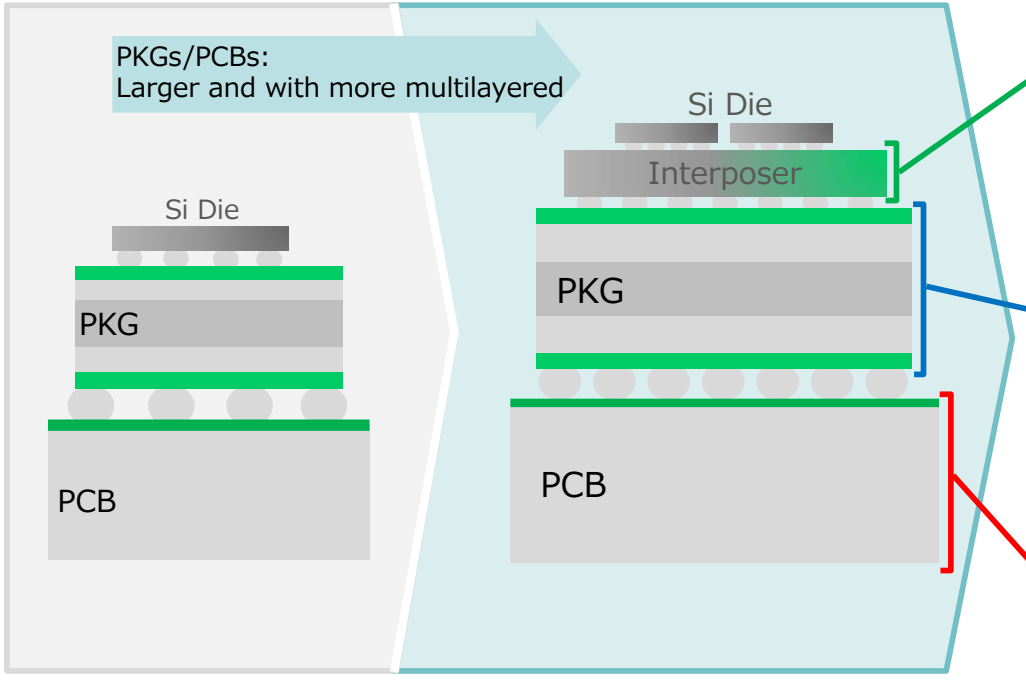
Our Products & PKG Substrate Trend



Aiming to Expand the Technical Domain

Evolution of Our Company's Technology and Required Technology

Ultra-high density, low signal loss, low power consumption



New field（Interposer）

・Products : Roughening adhesion(CZ)×Chemical adhesion(AP)
・Technical trend : Ultra-high density（Low L/S)
・Final products : Generative AI、Data centers

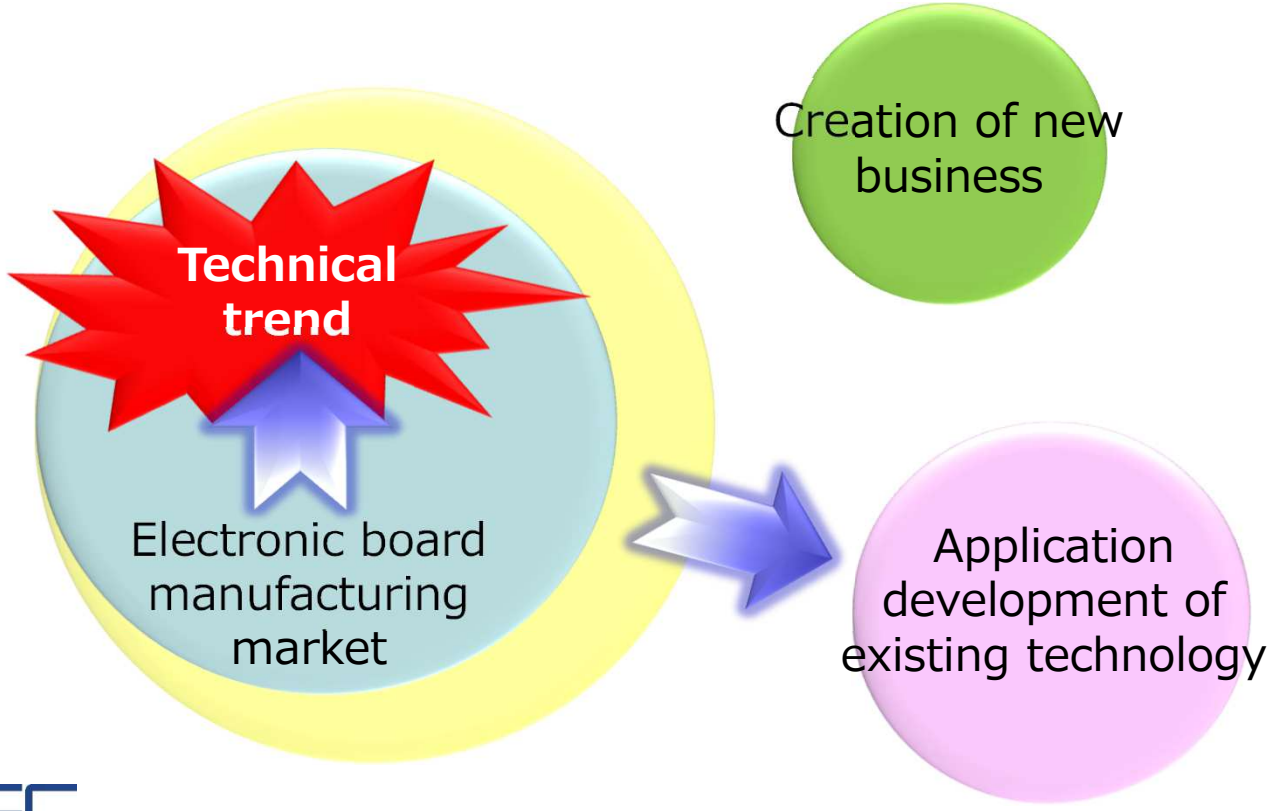
Existing field（PKG）

・Products : Roughening adhesion(CZ), Chemical adhesion(AP)
・Technical trend : High density（Low L/S)
Reduction of coarsening amount due to low Power consumption needs
・Final products : Generative AI、Data centers

New field（High-frequency）

・Products : Chemical adhesion(AP)
・Technical trend : Reduction of roughening amount due to low signal loss requirements
・Final products : Generative AI, Data centers, Semiconductor inspection equipment

Aiming to Expand the Business Domain



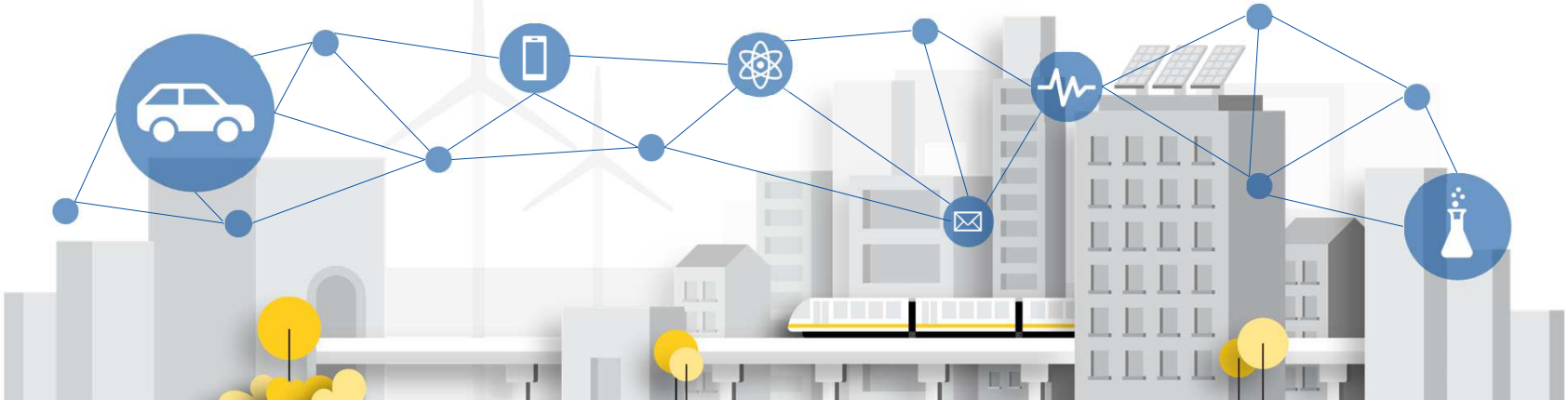
2030 Vision

Phase 2 First Year Progress and Future Initiatives

Medium-term Management Plan

(2025–2027)

February 13, 2026



Summary

- **Results for the first year of our 2030 Vision: Phase 2 exceeded initial expectations** against the backdrop of a favorable market environment, including increasing demand related to generative AI.

- **We have revised targets for FYE 12/2027,** the final year of Phase 2, considering the market environment and trends in demand for high value-added products.

➢ Net sales	¥25 billion	⇒	¥25 billion
Core business	¥23.5 billion	⇒	¥24.5 billion
Application and expansion	¥1.5 billion	⇒	¥0.5 billion
➢ Operating margin	at least 20%	⇒	26–30%
➢ ROE	at least 10%	⇒	13–16%

- To further enhance shareholder returns, **we have changed our dividend policy** in Phase 2 **to "a consolidated payout ratio of 35% or higher and a consolidated DOE (Dividend on Equity) of 4.0% or higher."**

This revision of quantitative targets is made within the framework of the existing medium-term management plan and does not involve any change in our strategic policies.

Quantitative Targets and Results

We clarified our management targets regarding profitability and capital efficiency, considering the market environment in which our Group operates and trends in demand for our high value-added products.

	FYE 12/2025 Results	FYE 12/2027 Initial Targets	FYE 12/2027 Revised Targets
Net sales	¥20.9 billion	¥25.0 billion Core business ¥23.5 billion Application and Expansion ¥1.5 billion	¥25.0 billion Core business ¥24.5 billion Application and Expansion ¥0.5 billion
Operating margin	27.4%	At least 20%	26–30%
ROE	17.5%	At least 10%	13–16%

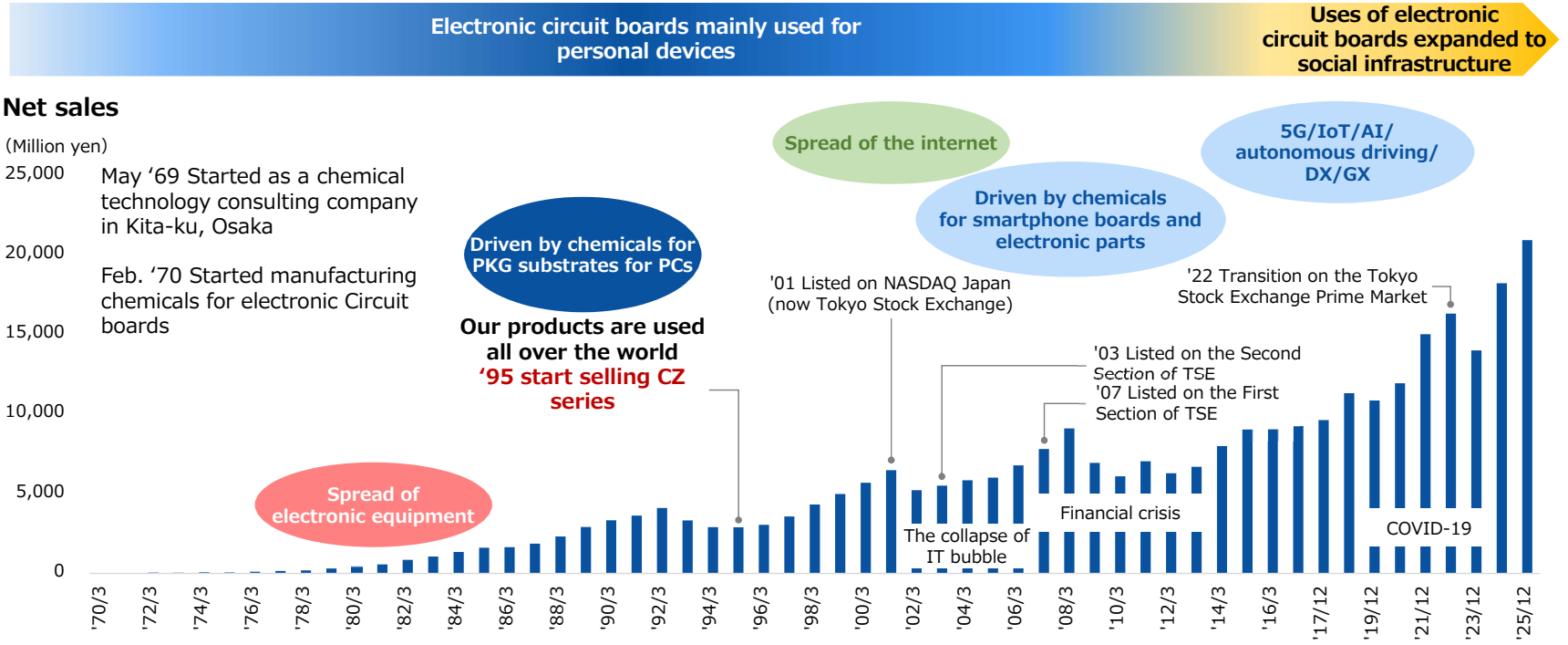
Appendix

Corporate Profile

(As of December 31, 2025)

Company name	MEC COMPANY LTD.
Head quarters location	3-4-1, Kuise Minamishimmachi, Amagasaki, Hyogo
Date of establishment	May 1, 1969
Business activities	R&D, production and sales of chemicals, equipment and related materials used in the production of PCBs and electronic components.
Presentative	President and CEO　　Kazuo Maeda
Capital	594,142,400 JPY
Net sales	20,947 million JPY (Consolidated)
Stock listing	Tokyo Stock Exchange Prime Market, Securities code: 4971
Number of employees	508 persons (Consolidated),292 persons (Non-consolidated)

MEC Sales Trend Since Foundation



*FYE 12/2017 is a period of nine months from April 1 to December 31 of 2017 due to the change of the accounting period. The consolidated period for MEC is a period of nine months (from April 1 to December 31 of 2017) while that for consolidated subsidiaries is a period of twelve months (from January 1 to December 31 of 2017).

Process of Commercialization

From R&D
To Factory

Beaker experiment ⇒ Scale-up experiment ⇒ Production line verification

To customers

Manufacturing ⇒ Quality inspection ⇒ Filling

Example of Product Usage Process

«Drying»

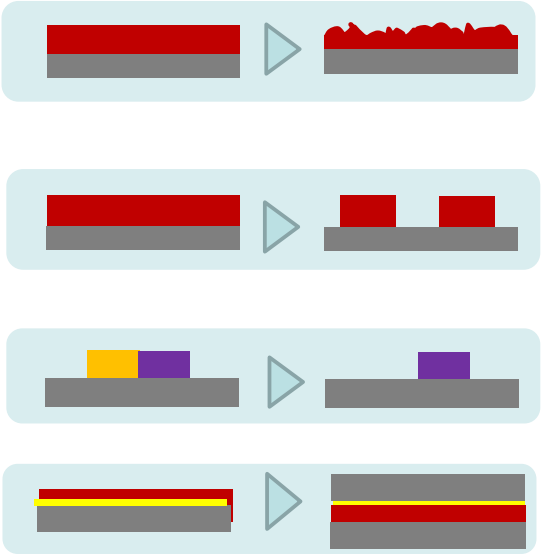
«Water rinse»

«Chemical treatment»

MEC's Core Technologies

Creating and Fostering Value at Various Interfaces

- **Roughen** the surface, and **physically** improve adhesion
  - CZ,V-Bond
- **Pattern formation**
  - EXE
- **Selective etching**
  - SF
- **Treat** the surface, and **chemically** adhesion promoter
  - AP

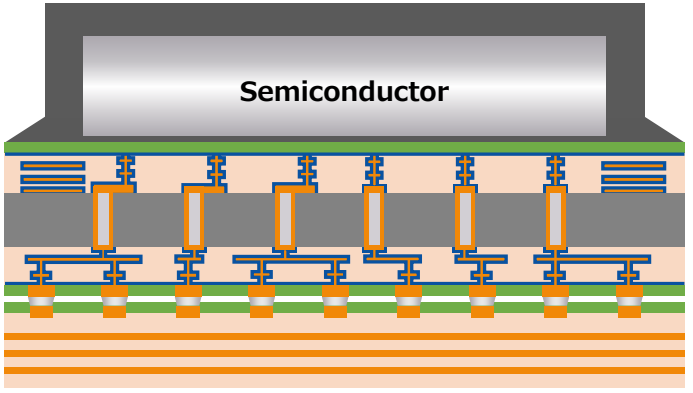


Examples of Major Chemical Applications and Final Products

Major chemical	Characteristic	Final products
Super-roughening type adhesive enhancement CZ series	A copper surface treatment agent that enhances adhesion between copper and resin. It is mainly an adhesion improver for PKG substrates, and is also used for high-density PCBs.	Infrastructure (Generative AI, 5G/6G-related, data centers, etc.) and high-function devices (PCs, smartphones, tablet PCs, etc.)
Adhesion improvers for multilayer substrates V-Bond series	A copper surface treatment agent that enhances adhesion between copper and resin. Adhesion improver mainly for multilayer substrates. Not used for PKG substrates.	Automobile, smartphones, Satellite communications etc.
Anisotropic etchant EXE series	Fine wiring can be formed through subtraction. Etching agent for COF substrates.	TV and PC monitors, etc.
Selective etchant SF series	Etching agent with selectivity to copper.	Tablet PCs, etc.

Our Strength: Interlayer Adhesion Technology

The CZ series, our main products, is used as an adhesion promoter in the parts where copper contacts with resin. It is an indispensable technology in the process of improving adhesion between the copper and the build-up resin of package substrates.



As package substrates become larger and adopt more layers

⇒ **The amount of CZ series used increases**

CZ-8101 1.0μm
L/S=15/15μm
Finely roughened

CZ-8201 0.5μm
L/S=15/15μm
Very finely roughened

CZ-8401 + series
(0.1μm + Chemical adhesion)
L/S=3/3μm
Super finely roughen + Organic adhesion promoter

Under development
0.0μm
(Chemical adhesion)
L/S=3/3μm
Flat organic adhesion promoter

Reduced etching volume

Changes in Copper Adhesion Surface Technology

Core Business: Package substrates

CZ-8100 — Roughening

Reduced etching volume

CZ-8101 — Fine roughening

Reduced etching volume Low signal loss

CZ-8201 — Ultra-fine roughening

Reduced etching volume Low signal loss

CZ-8401 × AP* — Ultra-fine roughening

Growing demand for roughening technology and non-roughening technology (chemical adhesion)

Demand for CZ-8101 is increasing in conjunction with expansion of related markets.
Demand for CZ-8201 and 8401 is increasing due to the need for reduced etching (demand for low loss)
AP, a non-roughening technology, is undergoing continuous evaluation and adoption and deepening of technology.
Even in areas other than package substrates, the demand for low signal loss is becoming more evident.

No roughening (Low signal loss)

AP* — No roughening (low signal loss)

Deployment of the same technologies on PCBs

Minimum Line Width [μm]

~60 | 40 | 20 | 10 | 0

Application and Expansion: PCBs (High-frequency substrates)

Fine roughening

No roughening (Low signal loss)

Against the backdrop of demand for low loss, demand for non-roughening technology will increase!

AP* — No roughening (Low signal loss)

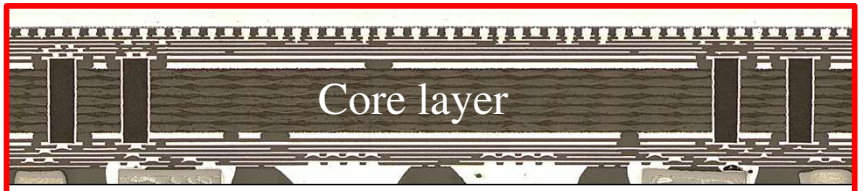
Expand the knowledge gained with package substrates to PCBs used in data centers and other applications using non-roughening technology.

~800G | 1.6T~

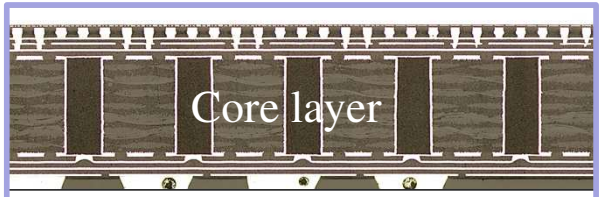
Ethernet communication speed [bE]

＊AP : Adhesion Promotor (Chemical adhesion using non-roughening technologies, chemical adhesion enhancement against fine roughening)

Cross Section Observations



XEON PKG 14 layers(6- 2 -6)



Core i7 PKG 8 layers(3-2-3)

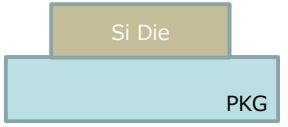
Ryzen PKG 12 layers(5-2-5)

	Size($cm^{2)}$	Layers
XEON	**27.44**	**14**
Core i7	**14.44**	**8**
Ryzen 7	**16.00**	**12**

Evolution of the PKG Substrate

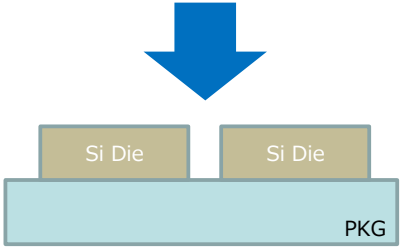
Conventional PKG substrate

One PKG, One Si Die



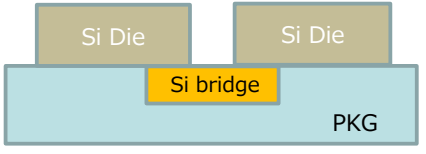
Advanced PKG substrate

Chiplet, 2.X/3D
Enlarging PKG to mount multiple semiconductors
- High-density PKG
- Large-size PKG
- High multi-layer PKG



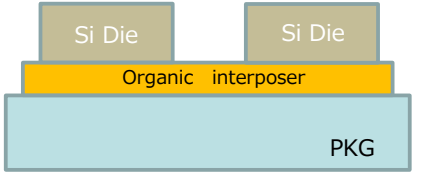
EMIB

(**E**mbedded **M**ulti-die **I**nterconnect **B**ridge)



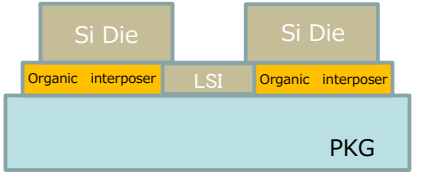
CoWoS-L

(**C**hip **o**n **W**afer **o**n **S**ubstrate)



CoWoS-R

(**C**hip **o**n **W**afer **o**n **S**ubstrate)



Production Capacity

Domestic base (Japan)

Amagasaki Factory
900 t / mo.

Nagaoka Factory
2,750 t / mo.

New production base
(Under construction)

Kitakyushu Plant (tentative name)
Maximum capacity 2,500 t /mo. (Plan)

Global base

MEC TAIWAN
1,200 t / mo.

MEC SUZHOU
1,350 t / mo.

MEC ZHUHAI
1,000 t / mo.

MEC EUROPE
400 t / mo.

MEC THAILAND
500 t / mo.

8,100 t/mo. (97,200 t/year) As of December 31, 2025

Creating and Fostering Value at Various Interfaces

This presentation includes forward-looking statements (such as predictions and business forecasts) made in February 13, 2026. These statements are assumptions based on information available at the time, and they are subject to risks and uncertainties. Actual results or events could differ substantially from those forecasted in such statements due to a plethora of variables.